

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	123	Masuda and Kazuhiro	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 16:55
L3	1	1 and level with boundary with substrate with interlayer adj dielectric	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 16:59
L4	3	1 and level and substrate and interlayer adj dielectric	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 16:59
L19	8219	through-hole and (cu copper)	US-PGPUB; USPAT	OR	OFF	2005/11/14 18:07
L20	582	through-hole and (cu copper) and passivation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:07
L21	12	through-hole and (cu copper) and passivation and hard adj mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:07
L22	2	(JP-2002050738-\$).did.	JPO; DERWENT	OR	OFF	2005/11/14 18:07
L27	5077	(257/758,774,776).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/14 18:07
L28	366	L27 and through-hole	US-PGPUB; USPAT	OR	ON	2005/11/14 18:07
L29	94	"4897708"	US-PGPUB; USPAT	OR	ON	2005/11/14 18:07
L31	2	"112961".ap. and @pd>"20020101"	US-PGPUB; USPAT	OR	OFF	2005/11/14 18:07
L32	12	(US-20030210534-\$ or US-20040251554-\$ or US-20040207089-\$).did. or (US-6848177-\$ or US-6486549-\$ or US-5399898-\$ or US-5432999-\$ or US-6184060-\$ or US-4954875-\$ or US-4728627-\$ or US-6664129-\$ or US-5394013-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/11/14 18:07

L33	12	L32 and (contact-hole through-hole via)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:07
L34	7239	(contact-hole through-hole via) with interlayer	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:07
L35	3	L32 and L34	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:07
L36	6249	(contact-hole through-hole via) with interlayer and substrate	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:07
L37	25489	(contact-hole through-hole via) and interlayer	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:07
L39	549	(contact-hole)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 18:07
L40	78818	(through-hole)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 18:07
L41	2506759	via	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 18:07
L42	2560901	L39 or L40 or L41	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 18:07
L43	8015	L42 with interlayer	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 18:07

L44	6915	L43 and substrate	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 18:07
L45	4366	L44 and electrode	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 18:07
L46	112072	silicon adj substrate	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:07
L47	2099	L43 and L46	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:07
L49	56643	(contact-hole through-hole)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:07
L52	19	(US-20020017710-\$ or US-20030008417-\$ or US-20030183921-\$ or US-20040164418-\$).did. or (US-4652970-\$ or US-4902637-\$ or US-5055914-\$ or US-5192988-\$ or US-5229647-\$ or US-5404046-\$ or US-5637925-\$ or US-5973927-\$ or US-5682062-\$ or US-6322903-\$ or US-6486549-\$ or US-6566232-\$ or US-6664129-\$ or US-6717254-\$ or US-6753205-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/11/14 18:07
L53	228	L49 with L46	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:22
L54	24	L43 and L53	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/14 18:23
S47	8	(US-20030025202-\$).did. or (US-6486549-\$ or US-5399898-\$ or US-5432999-\$ or US-6184060-\$ or US-4954875-\$ or US-4728627-\$ or US-6664129-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/11/14 14:30